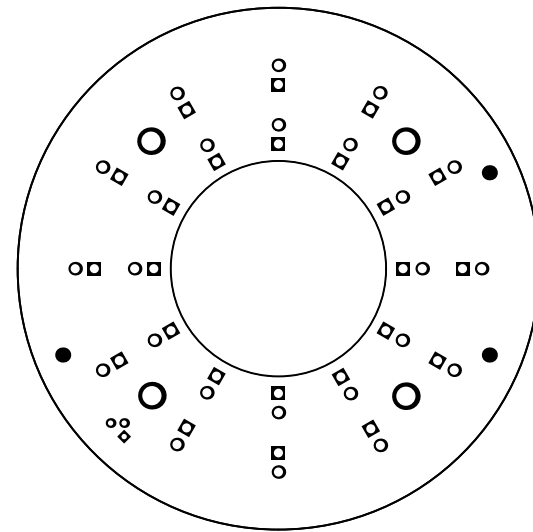
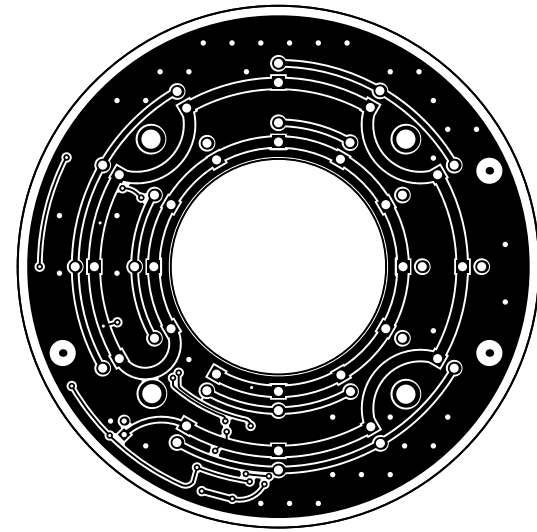


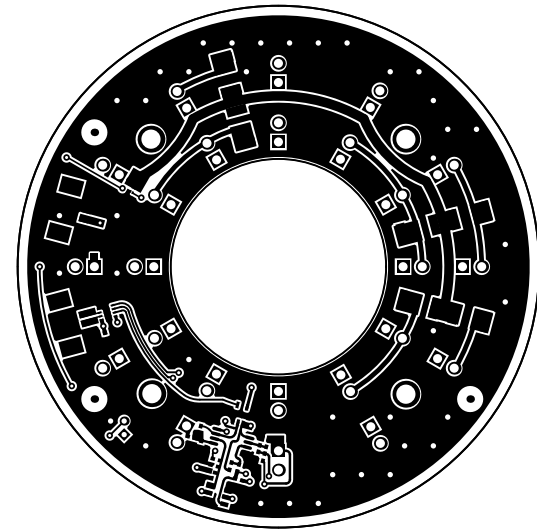
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01165	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 01165		
PLOT NAME = Top Overlay	GENERATED : 3/24/2017 11:06:24 AM		TEXAS INSTRUMENTS



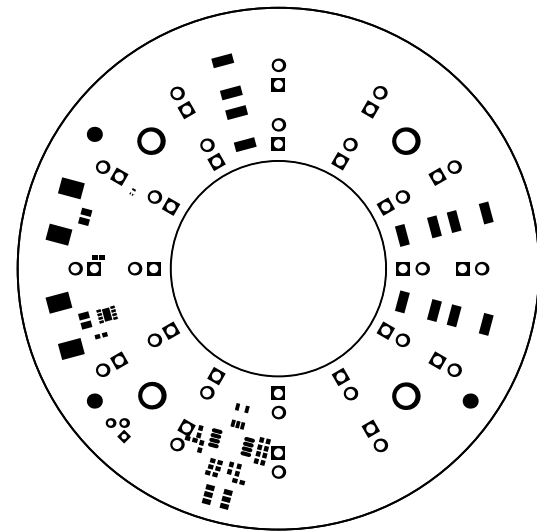
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01165	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: 01165		
PLOT NAME = Top Solder Mask	GENERATED : 3/24/2017 11:06:25 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01165	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: 01165		
PLOT NAME = Top Layer	GENERATED : 3/24/2017 11:06:25 AM	TEXAS INSTRUMENTS	

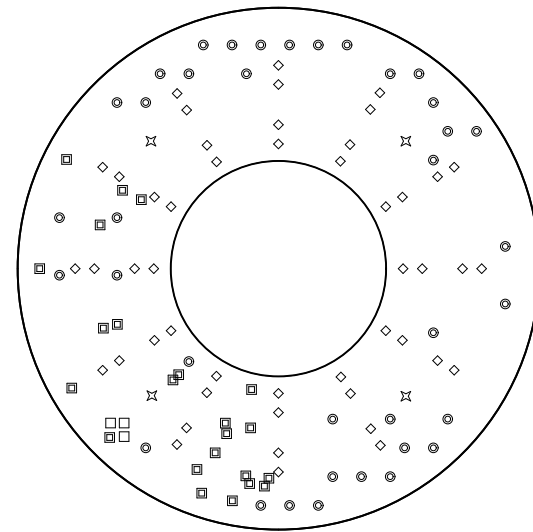


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01165	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: 01165		
PLOT NAME = Bottom Layer	GENERATED : 3/24/2017 11:06:25 AM	TEXAS INSTRUMENTS	



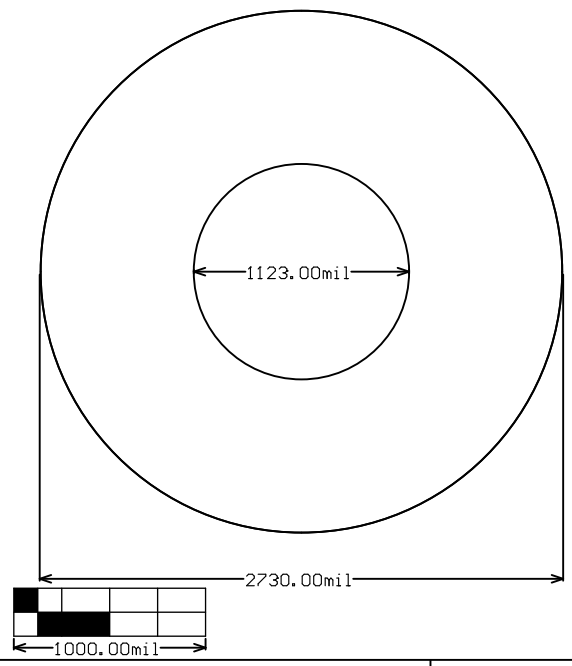
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01165	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 01165		
PLOT NAME = Bottom Solder Mask	GENERATED : 3/24/2017 11:06:25 AM	TEXAS INSTRUMENTS	





Symbol	Quantity	Finished Hole Size	Plated	Hole Type
■	23	16.00mil (0.406mm)	PTH	Round
□	3	27.56mil (0.700mm)	PTH	Round
●	37	28.00mil (0.711mm)	PTH	Round
◇	48	47.24mil (1.200mm)	PTH	Round
✕	4	100.00mil (2.540mm)	PTH	Round
	115 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01165	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 01165		
PLOT NAME = Drill Drawing	GENERATED : 3/24/2017 11:06:26 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01165	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: 01165		
PLOT NAME = Board Dimensions	GENERATED : 3/24/2017 11:06:26 AM	TEXAS INSTRUMENTS	



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